

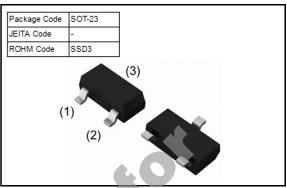
MMBZ27VALFH

Transient Voltage Suppressor

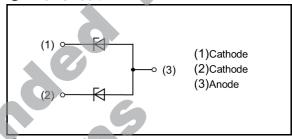
(AEC-Q101 qualified) Data sheet

V V_{RWM} 22.0 PPP 40 W Ipp 1.0 Α

Outline



Feature High reliability Small mold type Inner Circuit



Packaging Specification						
Packing	Embossed Tape					
Reel Size(mm)	180					
Taping Width(mm)	8					
Quantity(pcs)	3000					
Taping Code	T116					
Marking	D1D					

Application		Packa	ging Specificat	ion		
ESD Protection			Packing		Embossed Ta	
		R	eel Size(mm)		180	
		Tap Q	ing Width(mm)		8	
		0	uantity(pcs)		3000	
● Structure			aping Code		T116	
Silicon Epitaxial Planar			Marking			
				•		
● Absolute Maximum Rating (T _a =	= 25°C)					
Parameter	Symbol	Condition	ons	Min.	Max.	Unit
Peels Pides Parks	P _{PP1}	tp=10/10 MMBZ5V6AL ~N	-	24	W	
Peak Pulse Power	P _{PP2}	tp=10/10 MMBZ12VAL ~N	-	40	W	
Junction temperature	T _j -			-	150	°C
Storage temperature	T _{stg}	tg -			150	°C
Deven dissination			y substrate	-	225	mW
Power dissipation	P _{D2}	On Alumina substrate		-	300	mW
		IE004000 4 0	Air	-	30	kV
		IEC61000-4-2	Contact	-	30	kV
ESD capability*	V _{ESD}	Machine model		-	2	kV
ESD Capability	VESD	Human body model MIL-STD-883 level3			8	kV
		CDM (Charged device model)			500	V
	•	*IEC6100		C=1	50pF R=	:330Ω
		Machine	model		00pF R=	
		Human b	ody model	C=1	00pF R=	:1.5kΩ

● Characteristic (Ta = 25°C)

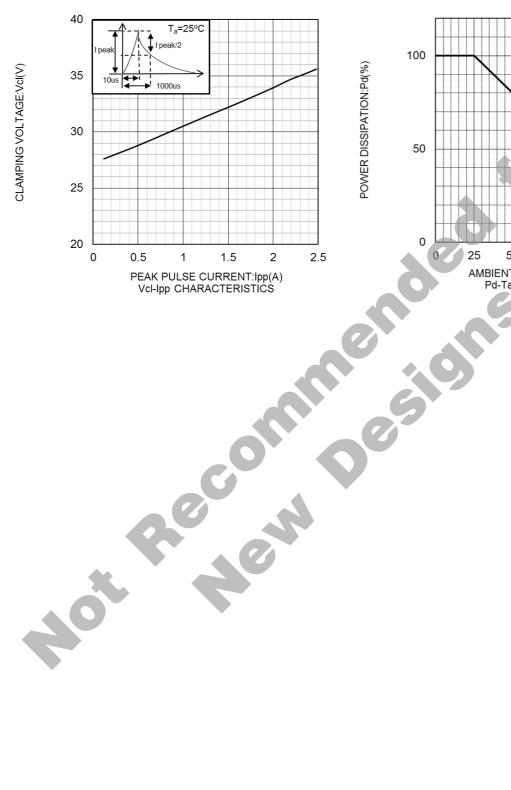
	Symbol								
P/N	Breakdown voltage : V _{B.R} (V)		Reverse Current : I _R (µA)		Forward voltage: V _F (V)		Reverse Stand-off voltage V _{RWM} (V)		
	MN.	Nom	MAX.	l _t (mA)	MAX.	V _R (V)	MAX.	I _F (mA)	MAX.
MMBZ5V6AL	5.32	5.60	5.88	20	5	3.0	0.9	10	3.0
MMBZ6V2AL	5.89	6.20	6.51	1	0.2	3.0	0.9	10	3.0
MMBZ6V8AL	6.46	6.80	7.14	1	0.3	4.5	0.9	10	4.5
MMBZ9V1AL	8.65	9.10	9.56	1	0.1	6.0	0.9	10	6.0
MMBZ10VAL	9.50	10.00	10.50	1	0.02	6.5	0.9	10	6.5
MMBZ12VAL	11.40	12.00	12.60	1	0.005	8.5	0.9	10	8.5
MMBZ15VAL	14.25	15.00	15.75	1	0.005	12.0	0.9	10	12.0
MMBZ16VAL	15.20	16.00	16.80	1	0.005	13.0	0.9	10	13.0
MMBZ18VAL	17.10	18.00	18.90	1	0.005	14.5	0.9	10	14.5
MMBZ20VAL	19.00	20.00	21.00	1	0.005	17.0	0.9	10	17.0
MVBZ24VAL	22.80	24.00	25.20	1	0.005	20.0	0.9	10	20.0
MMBZ27VAL	25.65	27.00	28.35	1	0.005	22.0	0.9	10	22.0
MMBZ30VAL	28.50	30.00	31.50	1	0.005	24.0	0.9	10	24.0
MMBZ33VAL	31.35	33.00	34.65	1	0.005	26.0	0.9	10	26.0

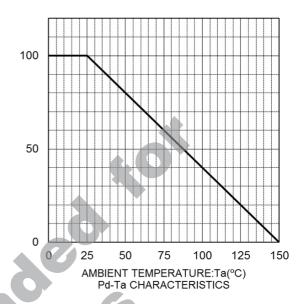
	MVBZ3UVAL	28.50	30.00	31.50	1	0.005	24.0	0.9	10	24.
	MMBZ33VAL	31.35	33.00	34.65	1	0.005	26.0	0.9	10	26.
Bre	eakdown voltage (V _l	_{BR}) is me	easured	by apply	ing curre	ent with 4	10ms pu	lse.		,
				Syn	nbol					
	P/N		e current : 0/1000us		g voltage: (V)	Capacitano termi Ct(
		M	۱X.	MAX.	lpp(A)	TYP.	VR(V)			
	MMBZ5V6AL	3.	00	8.0	3.00	230	0			
	MMBZ6V2AL	2.	76	8.7	2.76	180	0			
	MMBZ6V8AL	2.	50	9.6	2.50	165	0			
	MMBZ9V1AL	1.	70	14.0	1.70	120	0			
	MMBZ10VAL	1.	70	14.2	1.70	105_	0			
	MMBZ12VAL	2.	35	17	2.35	85	0			
	MMBZ15VAL	1.5	90	21	1.90	75	0			
	MMBZ16VAL	1.	70	23	1.70	70	0			
	MMBZ18VAL	1.	60	25	1.60	60	0			
	MMBZ20VAL	1.	40	28	1.40	55	0			
	MMBZ24VAL	1.:	25	32	1.25	46	0			
	MMBZ27VAL	1.	00	40	1.00	42	0			
	MMBZ30VAL	0.	95	43	0.95	38	0			
	MMBZ33VAL	0.	87	46	0.87	34	0			
						•				

Marking

形名	Marking	形名	Marking
MMBZ5V6AL	DOM	MMBZ16VAL	D0Y
MMBZ6V2AL	DON	MMBZ18VAL	D0Z
MMBZ6V8AL	D0P	MMBZ20VAL	D1A
MMBZ9V1AL	DOS	MMBZ24VAL	D1C
MMBZ10VAL	DOT .	MMBZ27VAL	D1D
MMBZ12VAL	D0V	MMBZ30VAL	D1E
MMBZ15VAL	D0X	MMBZ33VAL	D1F

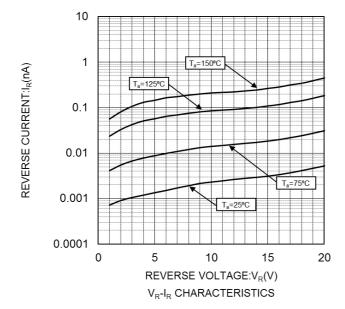
Characteristic Curves

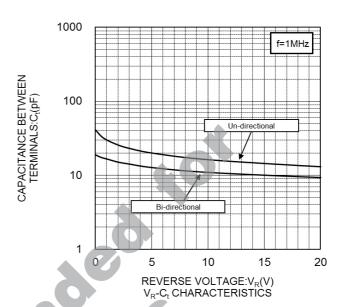


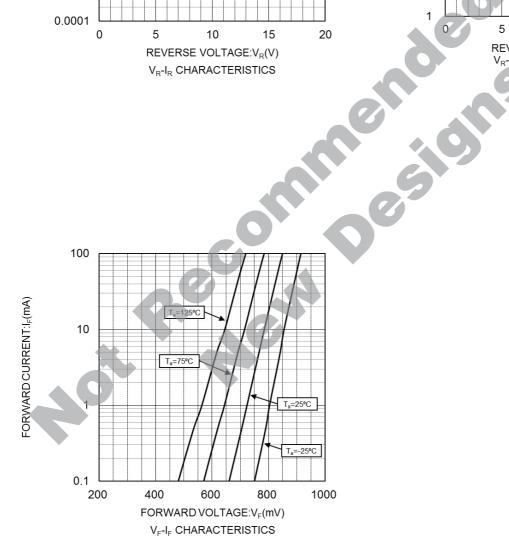


POWER DISSIPATION:Pd(%)

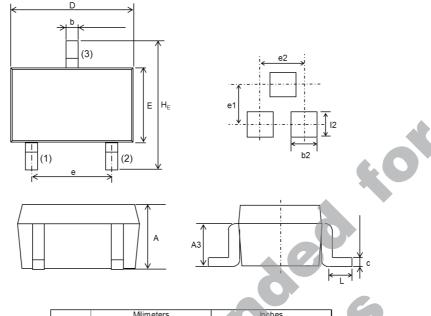
Characteristic Curves





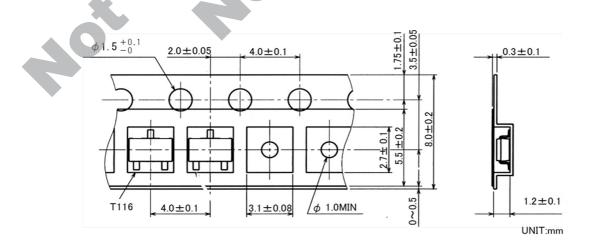


● Dimensions (SOT-23 SSD3)



DIM		Milimeters			Inches	
DIIVI	Min.	Average	Max.	Min.	Average	Max.
Α	0.85	0.95	1.15	0.033	0.037	0.045
A3	0.35	0.45	0.55	0.014	0.018	0.022
b	0.35	0.40	0.50	0.014	0.016	0.020
С	0.09	0.15	0.25	0.004	0.006	0.010
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.20	1.30	1.50	0.047	0.051	0.059
HE	2.20	2.40	2.60	0.087	0.094	0.102
L	0.20		-	0.008		-
е	1.70	1.90	2.10	0.067	0.075	0.083
12	1.00		-	0.039)	-
b2	0.80	-		0.031	-	
e1		2.10	- 4		0.083	-
e2		1.90	-	-	0.075	-

● Taping (Unit:mm)



Notice

Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSII	CL ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSⅢ	CLASSIII	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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